



Material Content Data Sheet



Sales Product Name	BAR 88-02LRH E6327			Issued		29. August 2013		
MA#	MA000252211							
Package	PG-TSLP-2-7			Weight*		0.51 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	non noble metal	tin	7440-31-5	0.000	0.07		710	
	noble metal	gold	7440-57-5	0.001	0.27		2749	
	inorganic material	silicon	7440-21-3	0.017	3.35	3.69	33546	37005
leadframe	non noble metal	nickel	7440-02-0	0.100	19.49	19.49	194863	194863
wire	noble metal	gold	7440-57-5	0.006	1.11	1.11	11061	11061
encapsulation	organic material	carbon black	1333-86-4	0.004	0.72		7195	
	plastics	epoxy resin	-	0.050	9.71		97142	
	inorganic material	silicondioxide	60676-86-0	0.316	61.52	71.95	615234	719571
leadfinish	noble metal	gold	7440-57-5	0.010	1.88	1.88	18750	18750
plating	noble metal	gold	7440-57-5	0.010	1.88	1.88	18750	18750
*deviation	< 10%	Sum in total:				100,00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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Company	Infineon Technologies AG
Address	81726 München
Internet	www.infineon.com